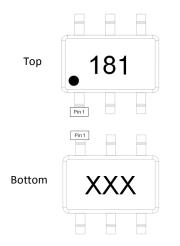
## TQP369181 DC-6 GHz Gain Block

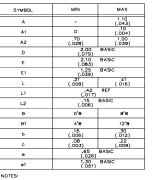


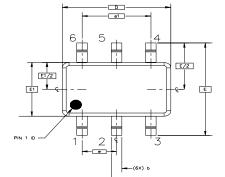
## **Mechanical Information**

## **Package Information and Dimensions**

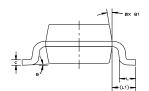
The component is marked on the top surface of the package with a "181" designator and on the bottom surface with an alphanumeric lot code.

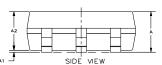






 DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1194, PACKAGE CONFORMS TO JEDEC MO-203, ISSUE B.
DIMENSIONS ARE IN MILLIMETERS (INCHES).





TOP VIEW

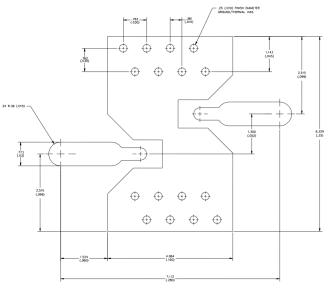
## **Mounting Configuration**

All dimensions are in millimeters (inches). Angles are in degrees.

Notes:

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- **3.** RF trace width depends upon the PC board material and construction.
- 4. Use 1 oz. Copper minimum

**Land Pattern** 



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